**MECHANICAL CASE OUTLINE**

**PACKAGE DIMENSIONS**

**ODCSP47 4.675x3.687**

**CASE 570AW**

**ISSUE 0**

**DATE 02 FEB 2023**

**NOTES:**

1. **DIMENSIONS IN MM. DIMENSIONS IN () ARE FOR REFERENCE ONLY.**
2. **ENCAPSULANT: EPOXY**
3. **SUBSTRATE MATERIAL: SILICON.**
4. **LID MATERIAL: BOROSILICATED GLASS 0.4 THICKNESS.**
5. **SOLDER BALL MATERIAL: SAC305 (96.5% Sn. 3% Ag, 0.5% Cu)**
6. **SOLDER BALL PADS #0.200 SMD**
7. **MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO PACKAGE EDGES: ±0.1°**
   **MAXIMUM TILT OF OPTICAL AREARELATIVE TO SUBSTRATE PLANE: 0° 2°UM.**
   **MAXIMUM TILT OF COVER GLASS RELATIVE TO OPTICAL AREA PLANE E: 2°UM**
8. **OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY AND IS NOT DELINEATED BY THE LIGHT BLOCK BOUNDARY. REFER TO THE DEVICE DATA SHEET FOR TOTAL ARRAY AND FIRST PIXEL DEFINITIONS.**

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